/ Descriptions

TO-251 NPN

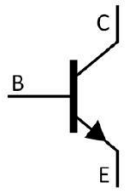
/ Features

$V_{CE(sat)}$,h_{FE}

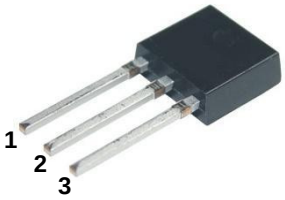
/ Applications

3 , ,

/ Equivalent Circuit



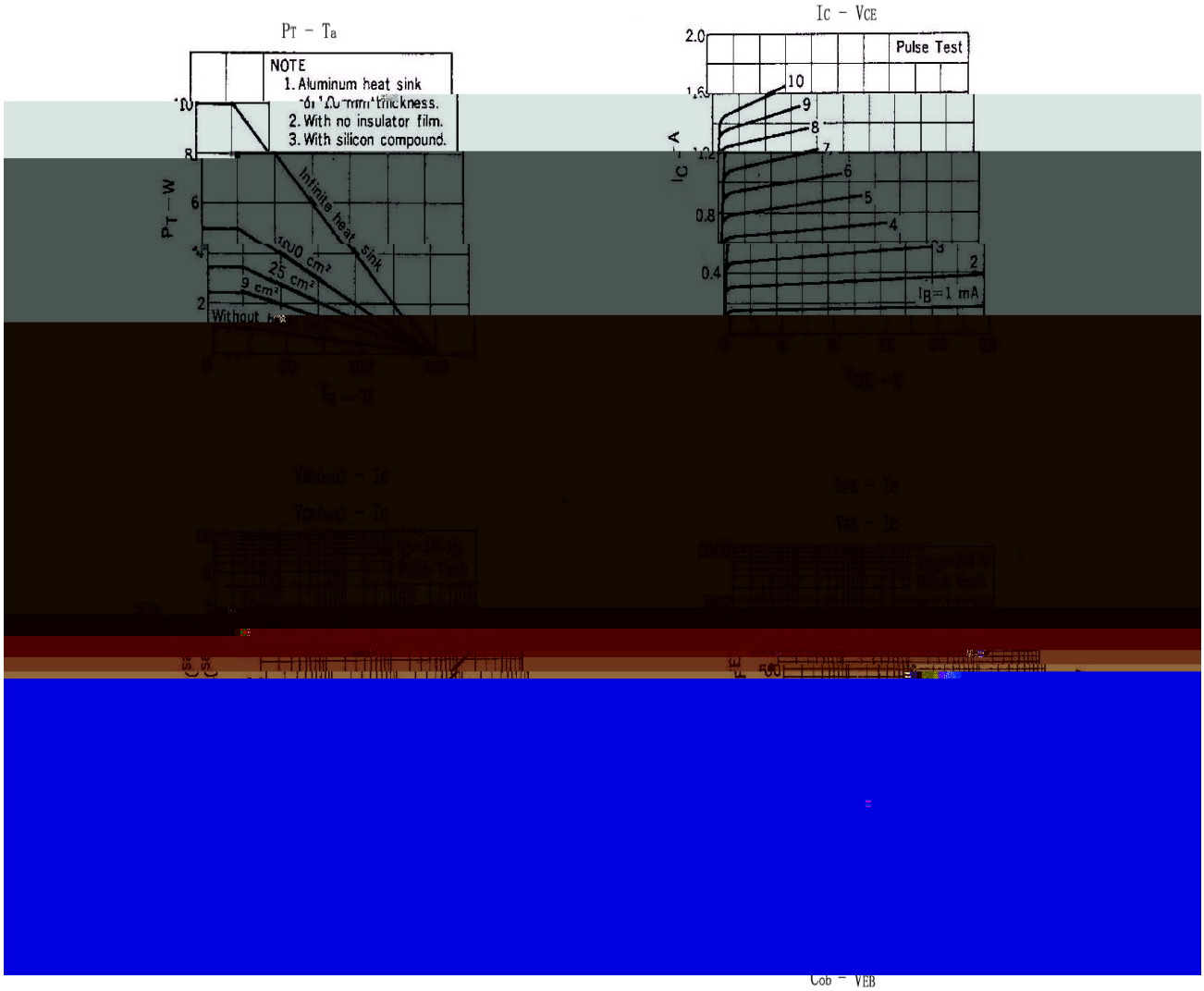
/ Pinning

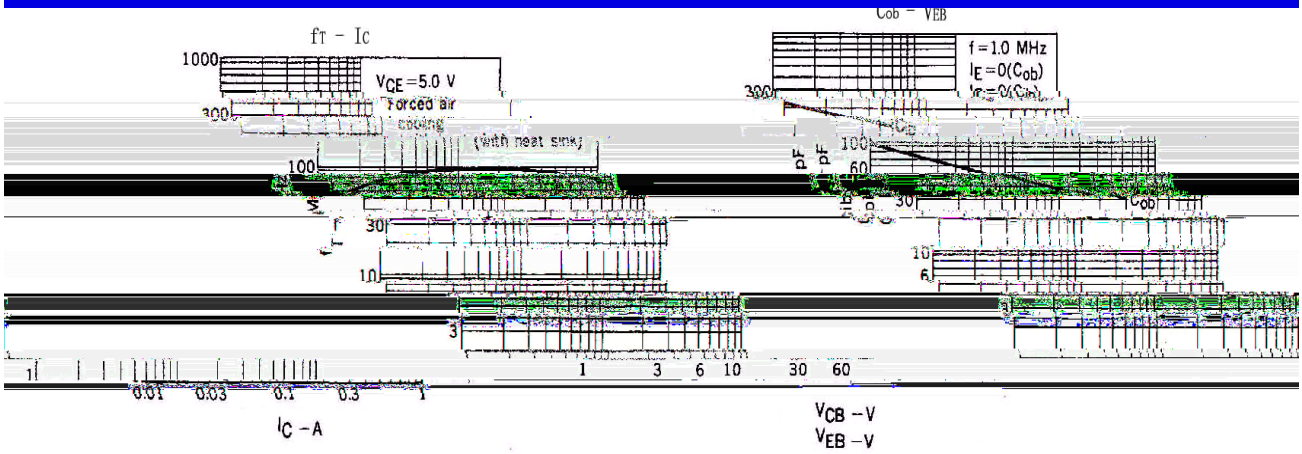


/ h_{FE} Classifications & Marking

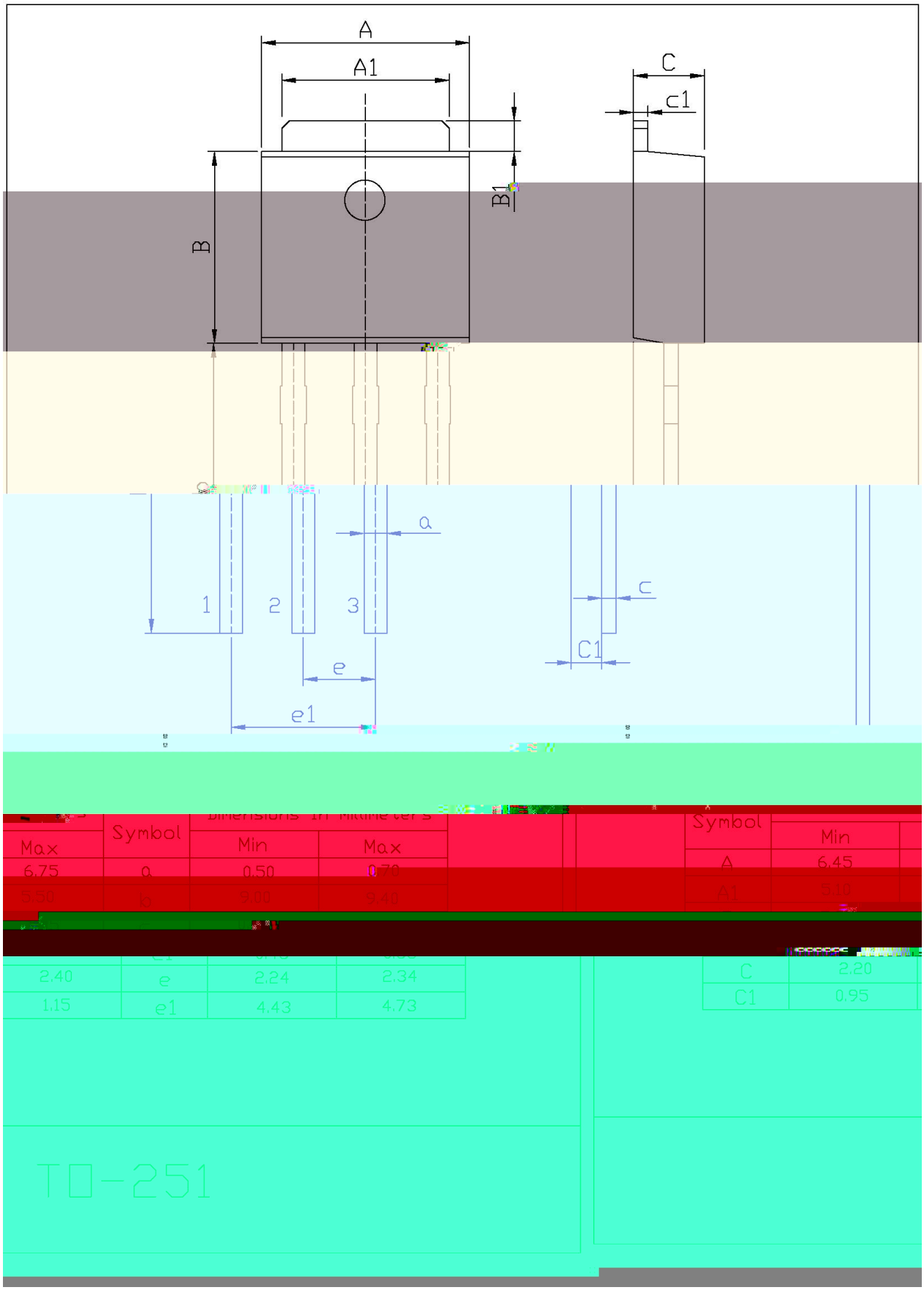
						μ
						μ

/ Electrical Characteristic Curve

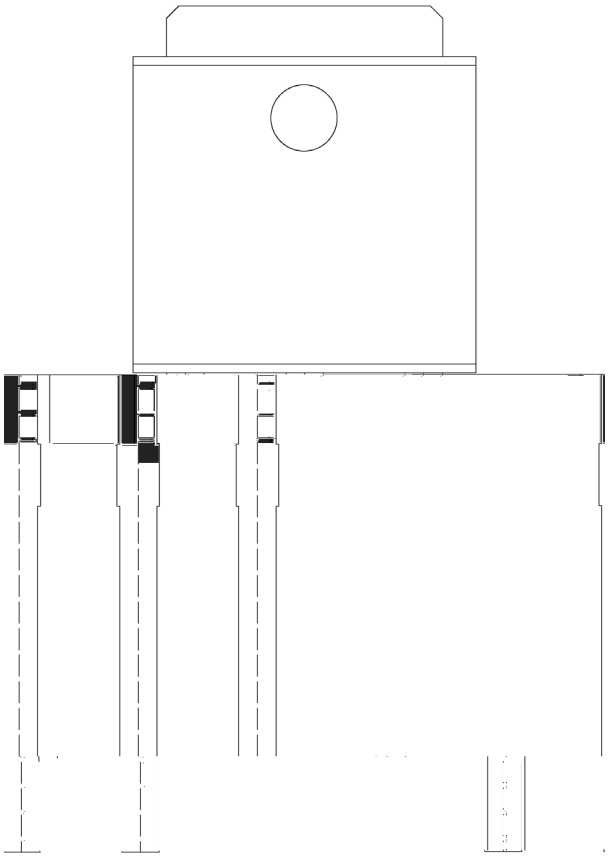




/ Package Dimensions



/ Marking Instructions



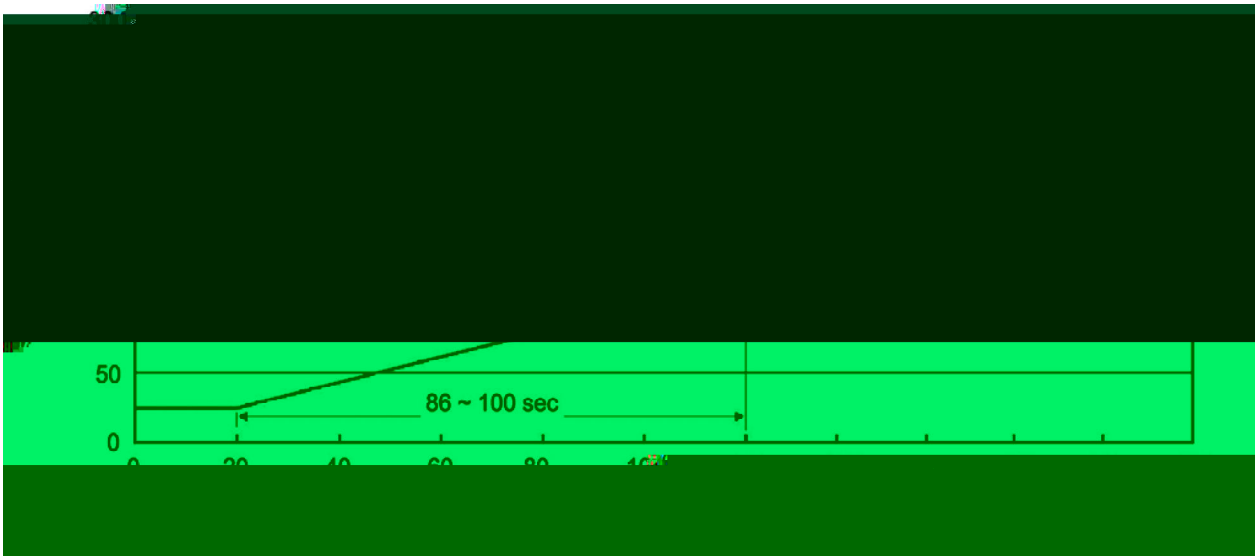
BR

D882I

R: h_{FE}

****

( ) / Temperature Profile for Dip Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

封装形式	包装数量					包装尺寸 :		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices